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ACHIEVE EXCEPTIONAL PLANENESS WITH HIGH REMOVAL FOR DIFFICULT APPLICATIONS

Available as a rigid surface

When working with very hard materials, brittle materials, composites or microelectronics with ceramic components, it can be difficult to obtain planeness, leading to the risk of relief.

The thoroughly tested and documented design of the metal-bonded MD-Diamond Pads ensures fast grinding steps with exceptional planeness. No matter your preparation goal you can achieve it even when preparing difficult applications.

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The MD-Diamond Pads comes in 3 grit sizes. MD-Diamond Pad 120 is the coarsest grinding surface in the range. Extensive testing from Struers R&D department shows that removal is not higher with a coarser surface.

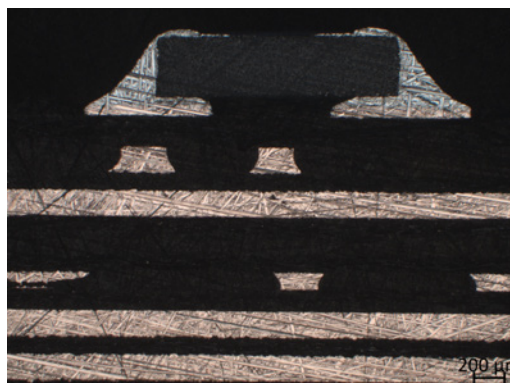


[Find your MD surfaces here >](#)

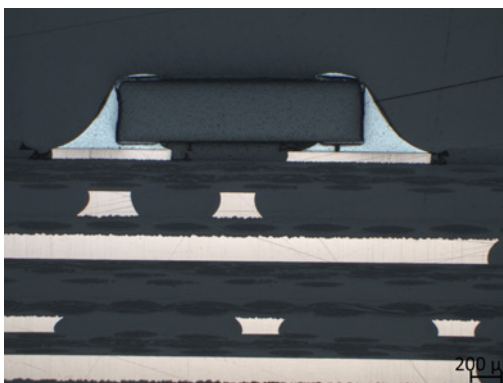
Preparation results

The final preparation result shows a high-quality result on difficult applications.

Microelectronics



Surface after Plane grinding with
MD-Diamond Pad 400 (x 50)



Surface after polishing with
MD-Chem & OP-U NonDry 0.04 µm (x 50)

Tungsten Carbide

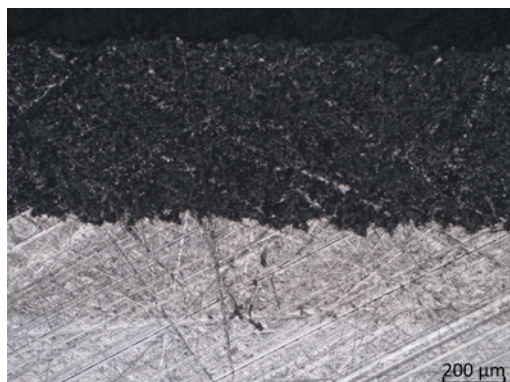


Surface after Plane grinding with
MD-Diamond Pad 800 (x 100)

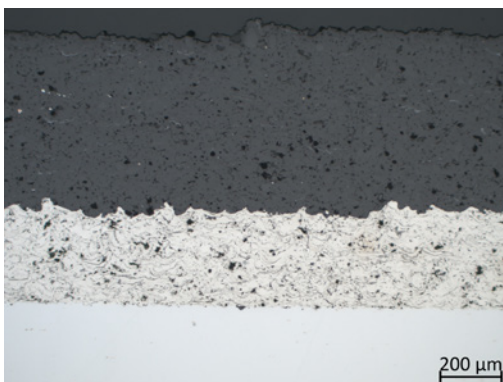


Surface after polishing with
MD-Plus & DiaPro Plus 3 µm (x 100)

Plasma Spray Coating



Surface after Plane grinding with
MD-Diamond Pad 400 (x 100)



Surface after polishing with
MD-Nap & DiaPro Nap B 1 µm (x 100)